

HEXFRED® Ultrafast Soft Recovery Diode, 140 A



SOT-227

FEATURES

- Fast recovery time characteristic
- Electrically isolated base plate
- Large creepage distance between terminal
- Simplified mechanical designs, rapid assembly
- Designed and qualified for industrial level
- UL approved file E78996
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


**RoHS
COMPLIANT**

PRIMARY CHARACTERISTICS	
V_R	600 V
V_F (typical)	1.33 V
t_{rr} (typical)	43 ns
$I_{F(DC)}$ at T_C , per module	140 A at 110 °C
$I_{F(AV)}$ at T_C , per module	140 A at 96 °C
Package	SOT-227

DESCRIPTION / APPLICATIONS

The dual diode series configuration VS-HFA140FA60 is used for output rectification or freewheeling/clamping operation and high voltage application.

The semiconductor in the SOT-227 package is isolated from the copper base plate, allowing for common heatsinks and compact assemblies to be built.

These modules are intended for general applications such as power supplies, battery chargers electronic welders, motor control and inverters.

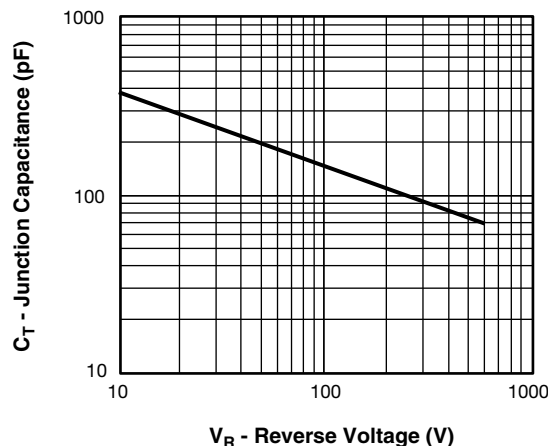
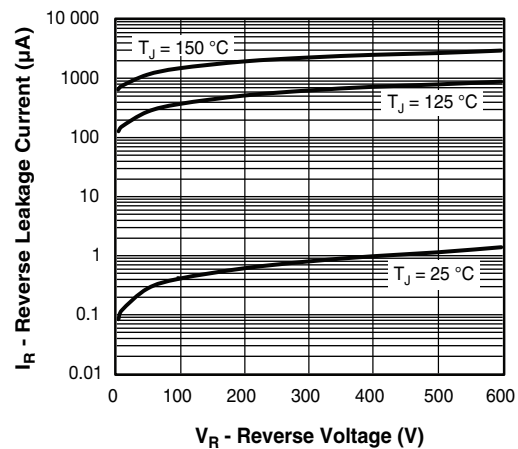
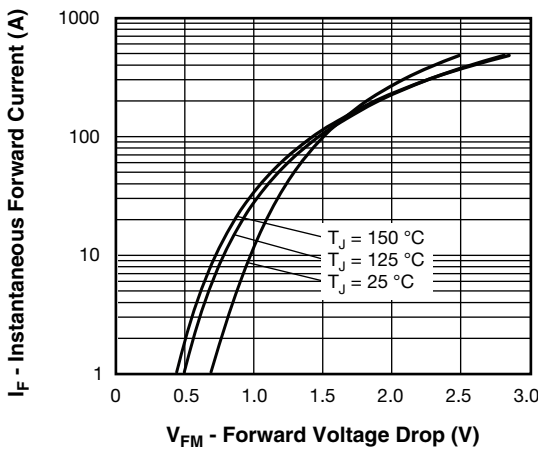
ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V_R		600	V
Continuous forward current	I_F	$T_C = 110\text{ °C}$	70	A
			140	
Single pulse forward current	I_{FSM}	$T_J = 25\text{ °C}$	600	
Maximum power dissipation, per leg	P_D	$T_C = 25\text{ °C}$	357	W
		$T_C = 110\text{ °C}$	114	
RMS isolation voltage	V_{ISOL}	Any terminal to case, $t = 1$ minute	2500	V
Operating junction and storage temperature range	T_J, T_{Stg}		-55 to +150	°C

ELECTRICAL SPECIFICATIONS ($T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage, per leg	V_{FM}	$I_F = 60\text{ A}$	-	1.33	1.70	
		$I_F = 120\text{ A}$	-	1.56	2.04	
		$I_F = 60\text{ A}, T_J = 125\text{ °C}$	-	1.24	-	
		$I_F = 60\text{ A}, T_J = 150\text{ °C}$	-	1.19	-	
Reverse leakage current, per leg	I_{RM}	$V_R = V_R$ rated	-	2.5	20	μA
		$T_J = 125\text{ °C}, V_R = V_R$ rated	-	0.8	2	mA
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	3	9	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time, per leg	t _{rr}	I _F = 1 A; di _F /dt = 200 A/μs; V _R = 30 V	-	43	-	ns
		T _J = 25 °C	-	90	-	
		T _J = 125 °C	-	150	-	
Peak recovery current, per leg	I _{RPM}	T _J = 25 °C	-	9.5	-	A
		T _J = 125 °C	-	17	-	
Reverse recovery charge, per leg	Q _{rr}	T _J = 25 °C	-	400	-	nC
		T _J = 125 °C	-	1180	-	
Junction capacitance, per leg	C _T	V _R = 600 V	-	67	-	pF

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction to case, single leg conducting	R _{thJC}		-	-	0.35	°C/W
Junction to case, both legs conducting			-	-	0.175	
Case to heatsink	R _{thCS}	Flat, greased surface	-	0.05	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
		Torque to heatsink	-	-	1.8 (15.9)	Nm (lbf.in)
Case style			SOT-227			



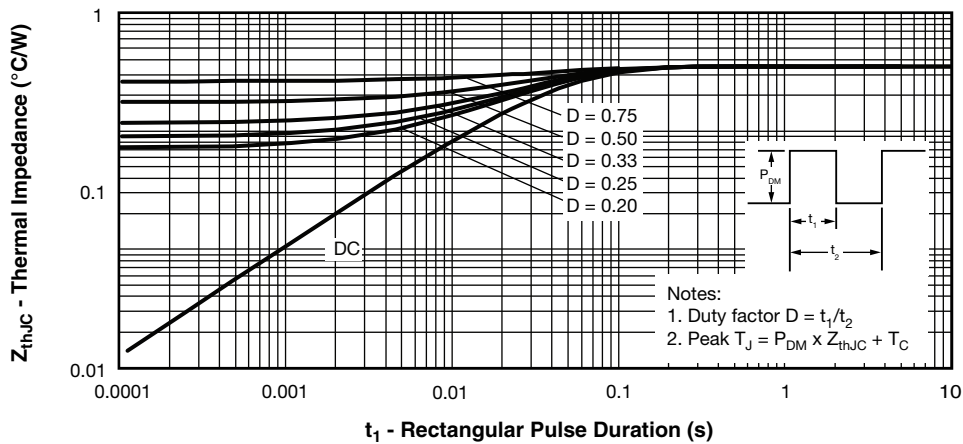


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

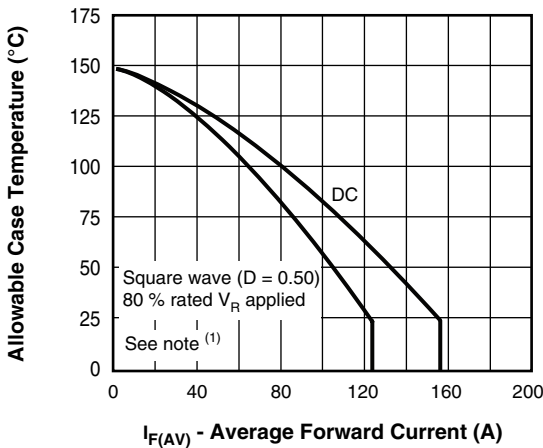


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current (Per Leg)

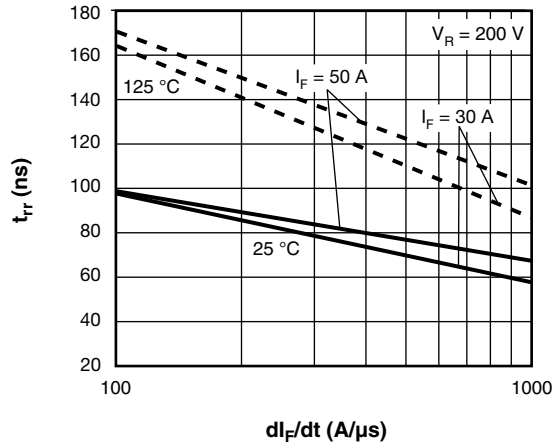


Fig. 7 - Typical Reverse Recovery Time vs. dI_F/dt

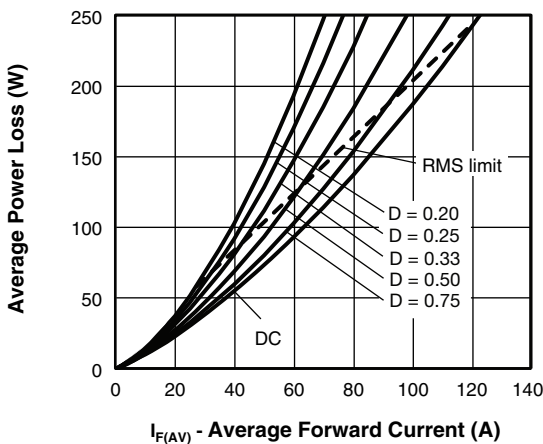


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

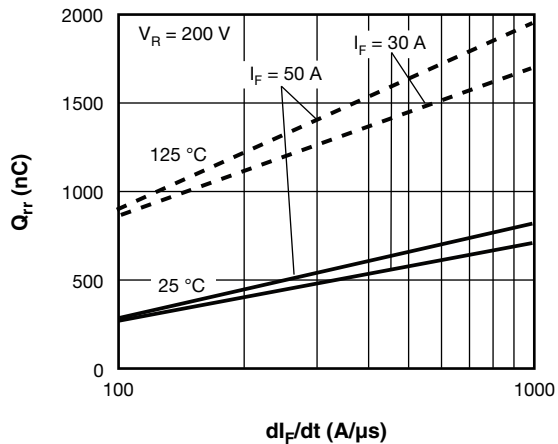


Fig. 8 - Typical Stored Charge vs. dI_F/dt

Note

- (1) Formula used: $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$;
 P_d = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 5);
 P_{dREV} = inverse power loss = $V_{R1} \times I_R (1 - D)$; I_R at V_{R1} = rated V_R

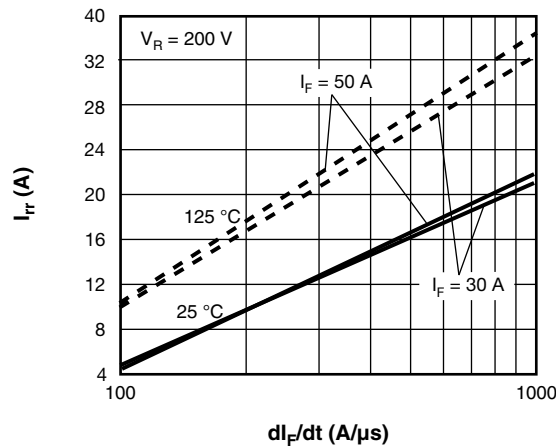


Fig. 9 - Typical Peak Recovery Current vs. di_F/dt

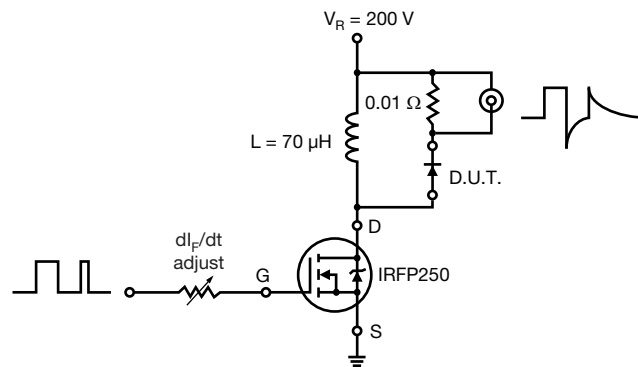
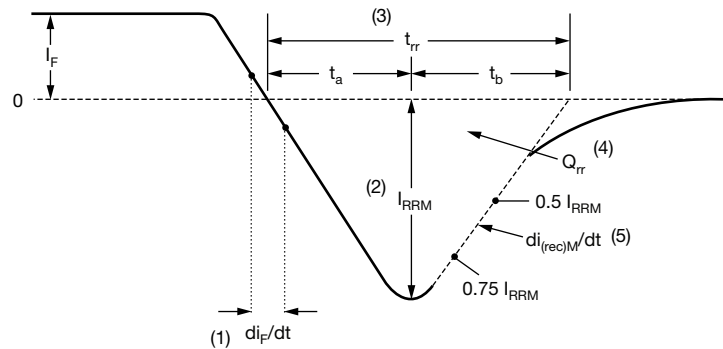


Fig. 10 - Reverse Recovery Parameter Test Circuit



- (1) di_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $di_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

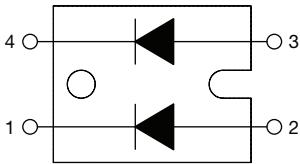
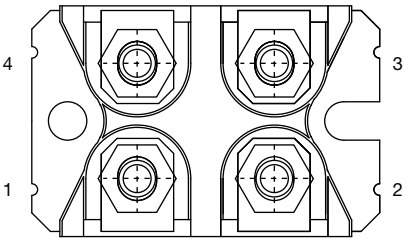
$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 11 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code	VS-	HF	A	140	F	A	60
	①	②	③	④	⑤	⑥	⑦

- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Process designator (A = electron irradiated)
- 4** - Average current (140 = 140 A)
- 5** - Circuit configuration (two separate diodes, parallel pin-out)
- 6** - Package indicator (SOT-227 standard insulated base)
- 7** - Voltage rating (60 = 600 V)

CIRCUIT CONFIGURATION		
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Two separate diodes, parallel pin-out	F	 

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95423
Part marking information	www.vishay.com/doc?95425



SOT-227 Generation 2

DIMENSIONS in millimeters (inches)



Note

- Controlling dimension: millimeter



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